

Supplementary Information for

Fabrication of Sinter-free Conductive Cu Paste using sub-10 nm Copper Nanoparticles

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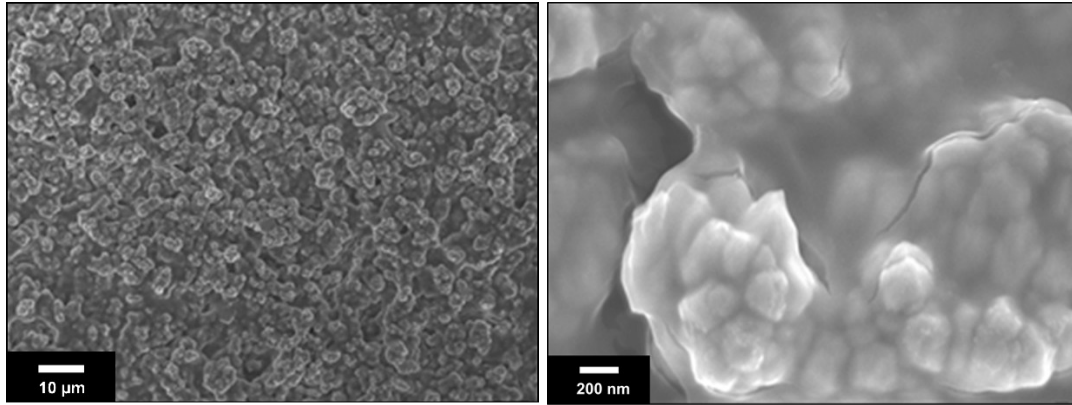


Figure S1. SEM images of CP-Cu Paste printed on a glass substrate. (thickness = 100 μm)

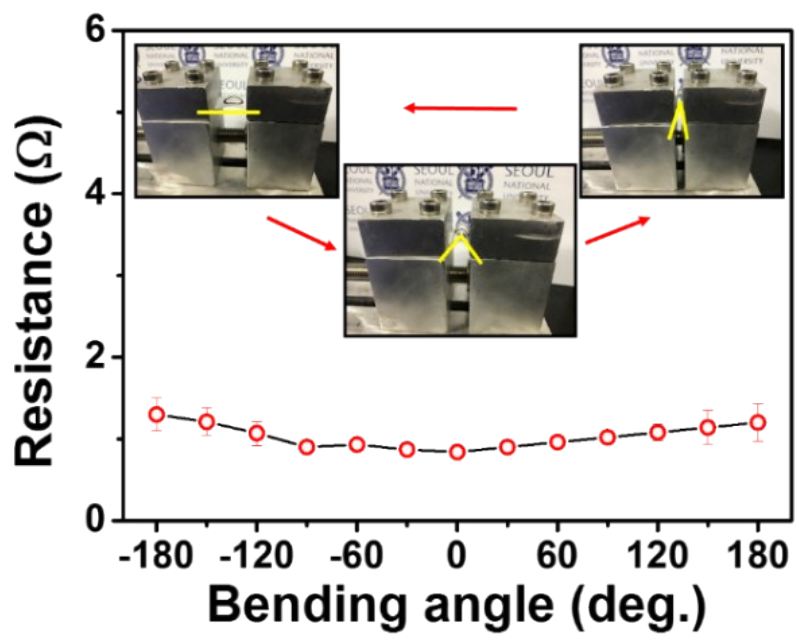


Figure S2. Bulk resistance changes of printed pattern of Cu NPs paste as a function of bending angle